

Features

- Low Power Consumption: 2µA (Typ)
- Maximum Output Current: 150mA
- Small Dropout Voltage 700mV@100mA (Vout=3.3V)
- High Input Voltage: Up to 80V
- High Accurate: HE2280(A) ±1% Output Voltage
- RoHS Compliant and Lead (Pb) Free
- Application
- Portable, Battery Powered Equipment
- Battery-powered equipment
- Weighting Scales

- Good Transient Response
- Integrated Short-Circuit Protection
- Over-Temperature Protection
- Output Current Limit
- Stable with Ceramic Capacitor
- Support Fixed Output Voltage 3.3 and 5.0V
- Available Package SOT23-3 \ SOT89-3
- Smoke detector and sensor
- Car Audio/Video Equipmen
- Home Automation

Description

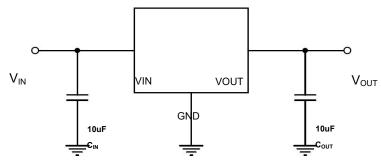
The HE2280 series is a high voltage, ultralow-power, low dropout voltage regulator. The device can deliver 150mA output current with a dropout voltage of 700mV and allows an input voltage as high as 80V. The typical quiescent current is only 2μ A. The device is available in fixed output voltages of 3.3,and 5.0V.The device features integrated short-circuit and thermal shutdown protection.Although designed primarily as fixed voltage regulators, the device can be used with external components to obtain variable voltages.

Selection Table

Part No.	Output Voltage	Package	Marking
HE2280A33PR	3.3V	SOT89-3	***
HE2280A50PR	5.0V	SOT89-3	***
HE2280A33MR	3.3V	SOT23-3	****
HE2280A50MR	5.0V	SOT23-3	****



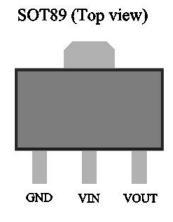
Application Circuits

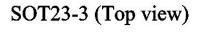


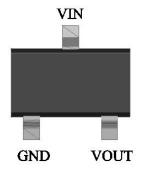
Note:External Component Recommendation:(VIN>45V)

- 1) CIN=100uF/100V(Electrolysis)
- 2) VIN/R1=50R(0805)

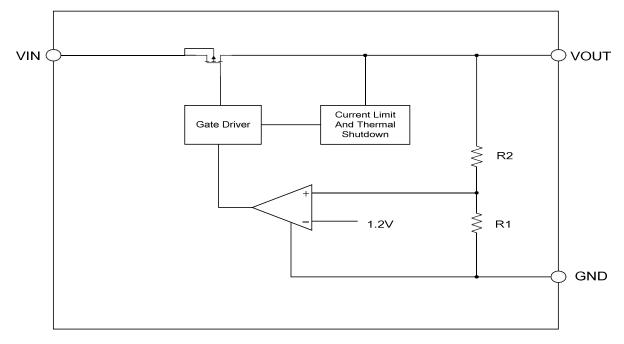
Pin Assignment







Function Block Diagram





Absolute Maximum Ratings (1) (2)

Paramete	er	Symbol	Maximum Rating	Unit	
Innut Voltore		VIN	V _{SS} -0.3~V _{SS} +80.0	V	
Input Volta	ige	νουτ	V _{SS} -0.3~V _{SS} +6.0	V	
Output Cur	rent	Ιουτ	400	mA	
Deuver Dissinction	SOT23-3	Pd	400	mW	
Power Dissipation	SOT89-3		500	11100	
Thermal Resistance	SOT23-3	R _{eja} ⁽³⁾	250	°C/W	
	SOT89-3	Reja	200	°C/W	
Operating Temperature		Topr	-40~85	°C	
Storage Temp	erature	Tstg	-40~125	°C	
Soldering Tempera	ture & Time	Tsolder	260 ℃, 10s		

Note (1): Exceeding these ratings may damage the device.

Note (2): The device is not guaranteed to function outside of its operating conditions

Note (3): The package thermal impedance is calculated in accordance to JESD 51-7.

ESD Ratings

Item	Description	Value	Unit
	Human Body Model (HBM)		
V(ESD-HBM)	ANSI/ESDA/JEDEC JS-001-2014	±4000	V
	Classification, Class: 2		
V(esd-cdm)	Charged Device Mode (CDM)		
	ANSI/ESDA/JEDEC JS-002-2014	±200	V
	Classification, Class: C0b		
I	JEDEC STANDARD NO.78E APRIL 2016	1450	
ILATCH-UP	Temperature Classification, Class: I	±150	mA

ESD testing is performed according to the respective JESD22 JEDEC standard. The human body model is a 100 pF capacitor discharged through a $1.5k\Omega$ resistor into each pin. The machine model is a 200pF capacitor discharged directly into each pin.

Recommended Operating Conditions

Parameter	MIN.	MAX.	Units
Supply voltage at VIN		60	V
Operating junction temperature range, Tj	-40	125	°C
Operating free air temperature range, TA	-40	85	°C

Note : All limits specified at room temperature (TA = 25°C) unless otherwise specified. All room temperature limits are 100% production tested. All limits at temperature extremes are ensured through correlation using standard Statistical Quality Control (SQC) methods. All limits are used to calculate Average Outgoing Quality Level (AOQL).



Electrical Characteristics

(Test Conditions:VIN= Vset+1V, VOUT=Vset,CIN=10uF, COUT=10uF,TA=25°C, unless otherwise specified.)

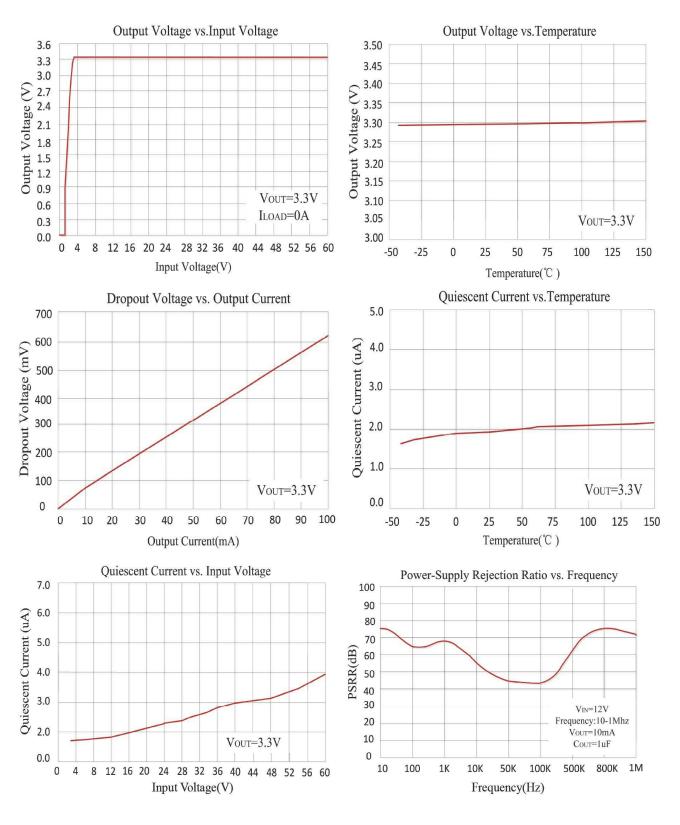
Parameter	Symbol	Conditions	Min	Тур	Max	Units
Input Voltage	Vin				80	V
Supply Current	lq	Vin=12V Iload=0mA	_	2.0	3.0	uA
Output Voltage HE2280 (A)	Vout1	Vin=12V Iout=10mA	Vset*0.99	Vset	Vset*1.01	V
Output Voltage HE2280 (B)	Vout2	Vin=12V Iout=10mA	Vset*0.98	Vset	Vset*1.02	V
Maximum Output Current	Ιουτ (Max)	_		200	_	mA
Dropout Voltago		Vin= Vset-0.1V Iout=10Ma	—	70	—	mV
Dropout Voltage	Vout=3.3V	ViN= Vset-0.1V Iou⊤=100mA	_	700	_	
Line Regulation	ΔVουτ / ΔVin•Vout	lout=1mA (Vset+0.5v)≦Vin≦55V	_	0.01	—	%/V
Load Regulation	ΔVουτ	Vin=12V 1mA≦Iout≦100mA	_	0.02	—	%/ mA
Short Current	Ishort	RL=1Ω	—	80	—	mA
Power Supply Rejection Rate	PSRR	VIN=12V VOUT=3.3V f=1KHz,Iout= 10mA	—	70	—	dB
Output Noise Voltage	e NO	Соυт=1uF BW = 300Hz~50kHz	—	50	—	uVrms
Output Voltage Temperature Coefficient	ΔVουτ/ ΔΤ•Vουτ	louτ=10mA	_	100	_	ppm/ ℃

Note: (1) Dropout Voltage is the voltage difference between the input and the output at which the output voltage drops 2% below its nominal value.

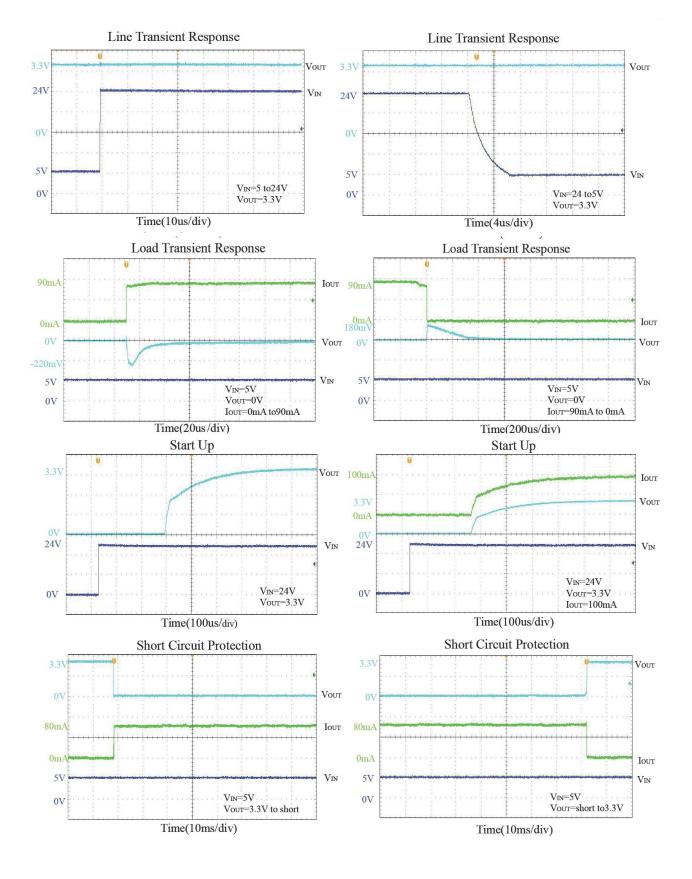


Typical Performance Characteristics:

Test Condition: TA=25°C,IouT=1mA, CouT=10uF, unless otherwise noted









Application Guideline

Input Capacitor

A 10 μ F ceramic capacitor is recommended to connect between V_{DD} and GND pins to decouple input power supply glitch and noise. The amount of the capacitance may be increased without limit. This input capacitor must be located as close as possible to the device to assure input stability and less noise. For PCB layout, a wide copper trace is required for both VIN and GND.

Output Capacitor

An output capacitor is required for the stability of the LDO. The recommended output capacitance is 10μ F, ceramic capacitor is recommended, and temperature characteristics are X7R or X5R. Higher capacitance values help to improve load/line transient response. The output capacitance may be increased to keep low undershoot/overshoot. Place output capacitor as close as possible to VOUT and GND pins.

Dropout Voltage

The dropout voltage refers to the voltage difference between the VIN and VOUT pins while operating at specific output current. The dropout voltage VDROP also can be expressed as the voltage drop on the pass-FET at specific output current (IRATED) while the pass-FET is fully operating at ohmic region and the pass-FET can be characterized as resistance RDS(ON). Thus the dropout voltage can bedefined as (VDROP = VIN - VOUT = RDS(ON) x IRATED). Fornormal operation, the suggested LDO operating range is (VIN > VOUT + VDROP) for good transient response and PSRR ability. Vice versa, while operating at the ohmic region will degrade the performance severely.

Thermal Application

For continuous operation, do not exceed the absolute maximum junction temperature. The maximum power dissipation depends on the thermal resistance of the IC package, PCB layout, rate of surrounding airflow, and difference between junction and ambient temperature. The maximum power dissipation can be calculated as below: TA=25°C, PCB,

The max PD= (125°C - 25°C) / (Thermal Resistance °C/W)

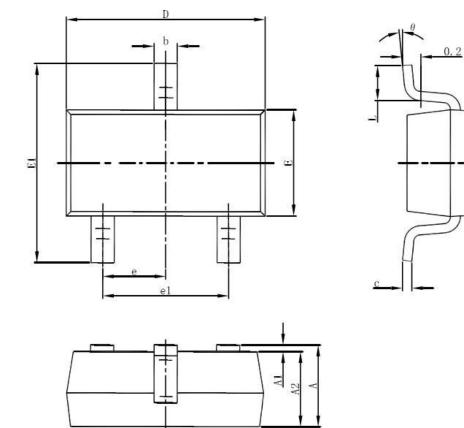
Power dissipation (PD) is equal to the product of the output current and the voltage drop across the output pass element, as shown in the equation below:

 $PD = (VIN - VOUT) \times IOUT$



Packaging Information

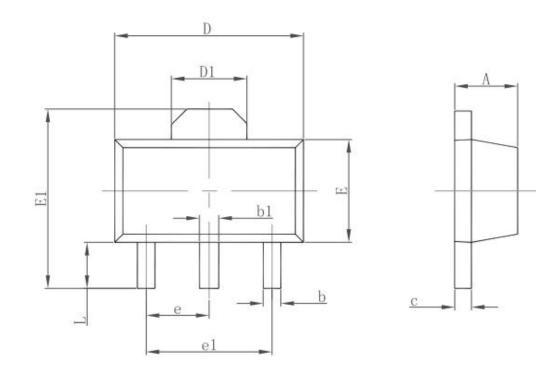
SOT23-3L



Symbol	Dimensions Ir	n Millimeters	Dimensions In Inches		
	Min	Max	Min	Max	
Α	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
C	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
Е	1.500	1.700	0.059	0.067	
E1	2.650	2.950	0.104	0.116	
е	0.950	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	



3-pin SOT89 Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.400	1.600	0.055	0.063
b	0.320	0.520	0.013	0.020
b1	0.400	0.580	0.016	0.023
С	0.350	0.440	0.014	0.017
D	4.400	4.600	0.173	0.181
D1	1.550 REF.		0.061 REF.	
E	2.300	2.600	0.091	0.102
E1	3.940	4.250	0.155	0.167
е	1.500 TYP.		0.060	TYP.
e1	3.000 TYP.		0.118 TYP.	
L	0.900	1.200	0.035	0.047